


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	ADG/22/13856	
<b>1.3 Title of PCN</b>	DPAK Big Die Dual Die line Transfer from Shenzhen to Tongfu Microelectronics (China)	
<b>1.4 Product Category</b>	Power MOSFET HV – IGBT – Power Bipolar	
<b>1.5 Issue date</b>	2022-12-22	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	KRAUSE INA
<b>2.1.2 Phone</b>	+49 89460062370
<b>2.1.3 Email</b>	ina.krause@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Maurizio GIUDICE, Angelo RAO
<b>2.1.2 Marketing Manager</b>	Paolo PETRALI, Natale Sandro D'ANGELO
<b>2.1.3 Quality Manager</b>	Vincenzo MILITANO

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Tongfu Microelectronics (China)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	DPAK Big Die Dual Die products are manufactured in Shenzhen (China)	DPAK Big Die Dual Die products are manufactured in Tongfu Microelectronics (China)
<b>4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?</b>	no impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	CAPACITY INCREASE
<b>5.2 Customer Benefit</b>	SERVICE CONTINUITY

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	By internal traceability and dedicated FG code
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2022-12-19
<b>7.2 Intended start of delivery</b>	2023-04-21
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	13856 Binder1.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2022-12-22

**9. Attachments (additional documentations)**

13856 Public product.pdf  
 13856 13856-DPAK Big Die Dual Die line Transfer from Shenzhen to TFME - IND.pdf  
 13856 Binder1.pdf  
 13856 Comparison DPAK A2 STS vs TFME C3.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STD13N60DM2	
	STD13NM60ND	
2729654	STD11N60DM2	
	STD16N65M2	
	STD5NM60T4	
	STD7LN80K5	
	STGD8NC60KDT4	

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